

$V_{DSS}$	1200V
$R_{DS(on)}$ (Typ.)	80mΩ
$I_D$	40A
$P_D$	262W

### ●Features

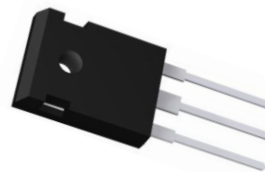
- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating ; RoHS compliant

### ●Application

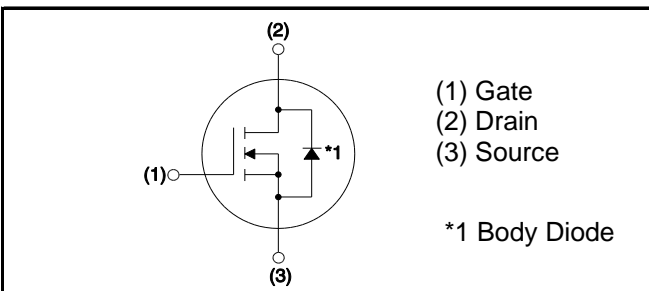
- Solar inverters
- DC/DC converters
- Induction heating
- Motor drives

### ●Outline

TO-247



### ●Inner circuit



### ●Packaging specifications

Type	Packing	Tube
	Reel size (mm)	-
	Tape width (mm)	-
	Basic ordering unit (pcs)	30
	Packing code	C
	Marking	SCT2080KE

### ●Absolute maximum ratings ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Value	Unit	
Drain - Source voltage	$V_{DSS}$	1200	V	
Continuous drain current	$T_c = 25^\circ\text{C}$	$I_D^{*1}$	40	A
	$T_c = 100^\circ\text{C}$	$I_D^{*1}$	28	A
Pulsed drain current	$I_{D,pulse}^{*2}$	80	A	
Gate - Source voltage (DC)	$V_{GSS}$	-6 to 22	V	
Gate - Source surge voltage ( $T_{surge} < 300\text{nsec}$ )	$V_{GSS-surge}^{*3}$	-10 to 26	V	
Power dissipation ( $T_c = 25^\circ\text{C}$ )	$P_D$	262	W	
Junction temperature	$T_j$	175	$^\circ\text{C}$	
Range of storage temperature	$T_{stg}$	-55 to +175	$^\circ\text{C}$	

### ●Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction - case	$R_{thJC}$	-	0.44	0.57	°C/W
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	50	°C/W
Soldering temperature, wavesoldering for 10s	$T_{sold}$	-	-	265	°C

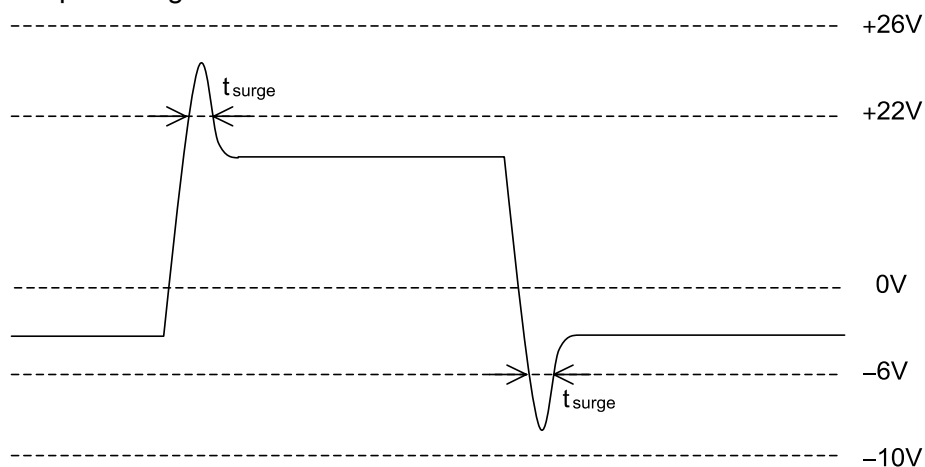
### ●Electrical characteristics ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 1mA$	1200	-	-	V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 1200V, V_{GS} = 0V$	-	1	10	$\mu\text{A}$
		$T_j = 150^\circ\text{C}$	-	2	-	
Gate - Source leakage current	$I_{GSS+}$	$V_{GS} = +22V, V_{DS} = 0V$	-	-	100	nA
Gate - Source leakage current	$I_{GSS-}$	$V_{GS} = -6V, V_{DS} = 0V$	-	-	-100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 4.4mA$	1.6	2.8	4.0	V

\*1 Limited only by maximum temperature allowed.

\*2  $PW \leq 10\mu\text{s}$ , Duty cycle  $\leq 1\%$

\*3 Example of acceptable Vgs waveform



\*4 Pulsed

**●Electrical characteristics (T<sub>a</sub> = 25°C)**

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Static drain - source on - state resistance	R <sub>DS(on)</sub> <sup>*4</sup>	V <sub>GS</sub> = 18V, I <sub>D</sub> = 10A T <sub>j</sub> = 25°C T <sub>j</sub> = 125°C	- -	80 125	117 -	mΩ
Gate input resistance	R <sub>G</sub>	f = 1MHz, open drain	-	6.3	-	Ω
Transconductance	g <sub>fs</sub> <sup>*4</sup>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 10A	-	3.7	-	S
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	2080	-	pF
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 800V	-	77	-	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	16	-	
Effective output capacitance, energy related	C <sub>o(er)</sub>	V <sub>GS</sub> = 0V V <sub>DS</sub> = 0V to 500V	-	116	-	pF
Turn - on delay time	t <sub>d(on)</sub> <sup>*4</sup>	V <sub>DD</sub> = 400V, V <sub>GS</sub> = 18V	-	35	-	ns
Rise time	t <sub>r</sub> <sup>*4</sup>	I <sub>D</sub> = 10A	-	36	-	
Turn - off delay time	t <sub>d(off)</sub> <sup>*4</sup>	R <sub>L</sub> = 40Ω	-	76	-	
Fall time	t <sub>f</sub> <sup>*4</sup>	R <sub>G</sub> = 0Ω	-	22	-	
Turn - on switching loss	E <sub>on</sub> <sup>*4</sup>	V <sub>DD</sub> = 600V, I <sub>D</sub> = 10A V <sub>GS</sub> = 18V/0V R <sub>G</sub> = 0Ω, L = 500μH	-	174	-	μJ
Turn - off switching loss	E <sub>off</sub> <sup>*4</sup>	*E <sub>on</sub> includes diode reverse recovery	-	51	-	

**●Gate Charge characteristics (T<sub>a</sub> = 25°C)**

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Total gate charge	Q <sub>g</sub> <sup>*4</sup>	V <sub>DD</sub> = 400V	-	106	-	nC
Gate - Source charge	Q <sub>gs</sub> <sup>*4</sup>	I <sub>D</sub> = 10A	-	27	-	
Gate - Drain charge	Q <sub>gd</sub> <sup>*4</sup>	V <sub>GS</sub> = 18V	-	31	-	
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> = 400V, I <sub>D</sub> = 10A	-	9.7	-	V

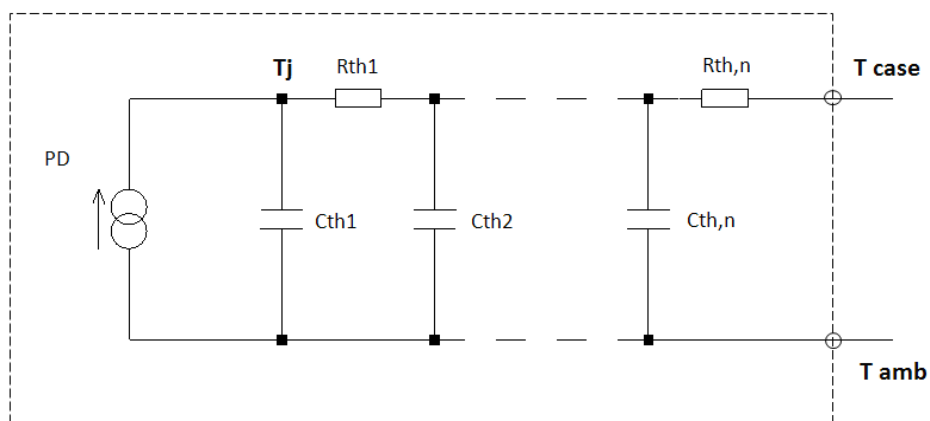
●Body diode electrical characteristics (Source-Drain) ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Inverse diode continuous, forward current	$I_S^{*1}$	$T_c = 25^\circ\text{C}$	-	-	40	A
Inverse diode direct current, pulsed	$I_{SM}^{*2}$		-	-	80	A
Forward voltage	$V_{SD}^{*4}$	$V_{GS} = 0\text{V}, I_S = 10\text{A}$	-	4.6	-	V
Reverse recovery time	$t_{rr}^{*4}$	$I_F = 10\text{A}, V_R = 400\text{V}$ $di/dt = 150\text{A}/\mu\text{s}$	-	31	-	ns
Reverse recovery charge	$Q_{rr}^{*4}$		-	44	-	nC
Peak reverse recovery current	$I_{rrm}^{*4}$		-	2.3	-	A

●Typical Transient Thermal Characteristics

Symbol	Value	Unit
$R_{th1}$	0.078	K/W
$R_{th2}$	0.197	
$R_{th3}$	0.162	

Symbol	Value	Unit
$C_{th1}$	0.005	Ws/K
$C_{th2}$	0.018	
$C_{th3}$	0.249	



●Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

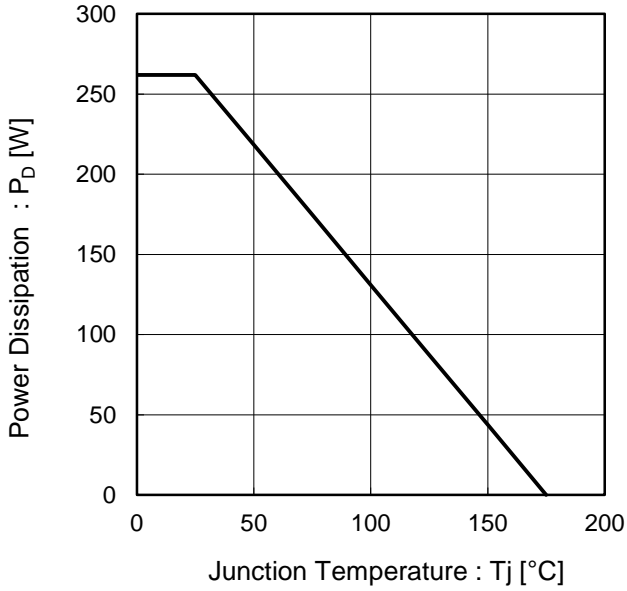


Fig.2 Maximum Safe Operating Area

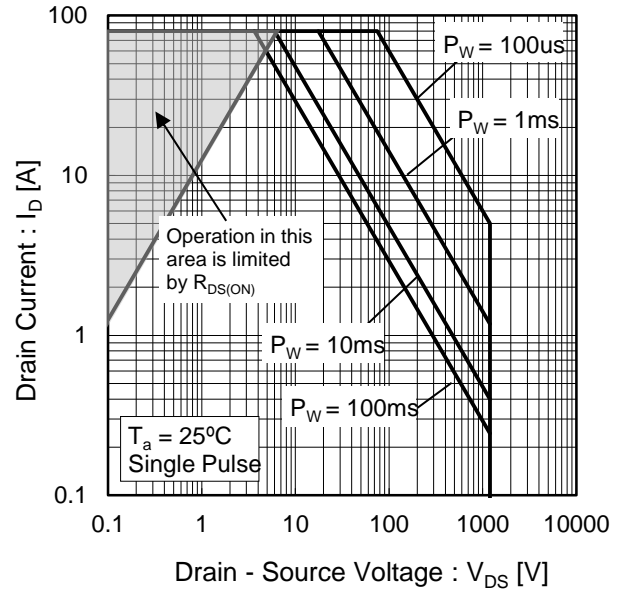
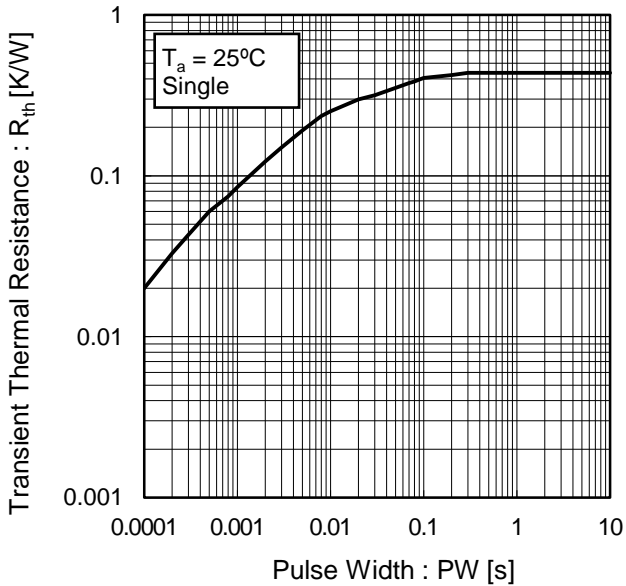


Fig.3 Typical Transient Thermal Resistance vs. Pulse Width



●Electrical characteristic curves

Fig.4 Typical Output Characteristics(I)

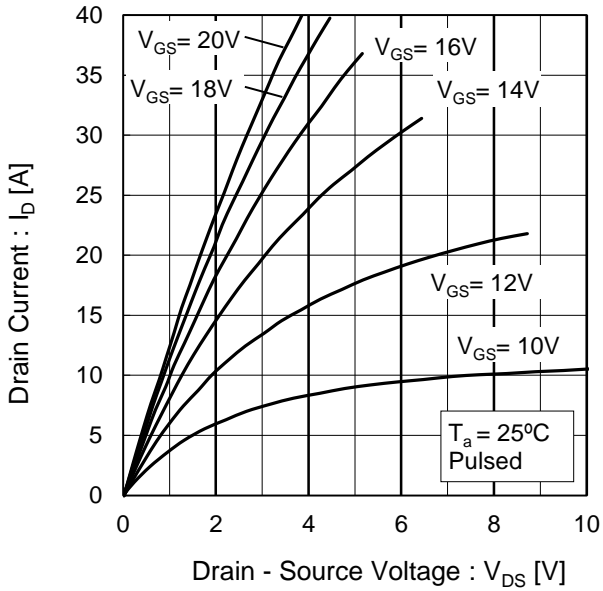


Fig.5 Typical Output Characteristics(II)

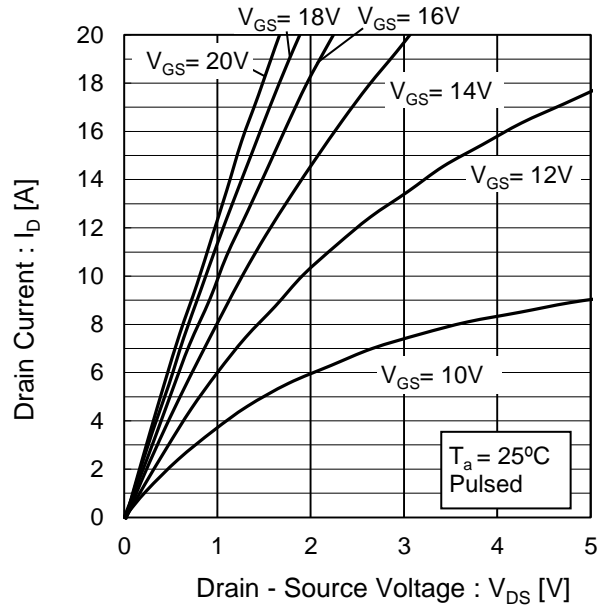


Fig.6 Typical Output Characteristics(I)

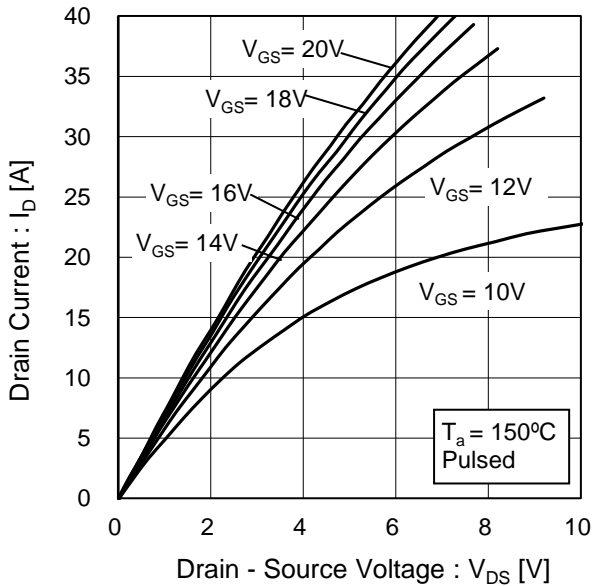
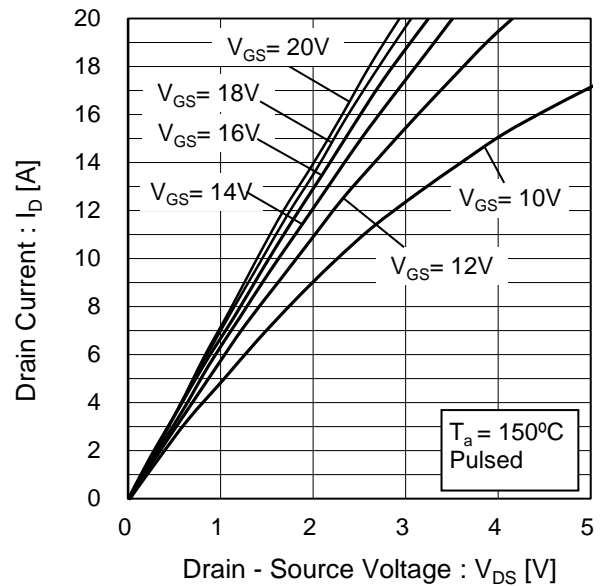


Fig.7 Typical Output Characteristics(II)



●Electrical characteristic curves

Fig.8 Typical Transfer Characteristics

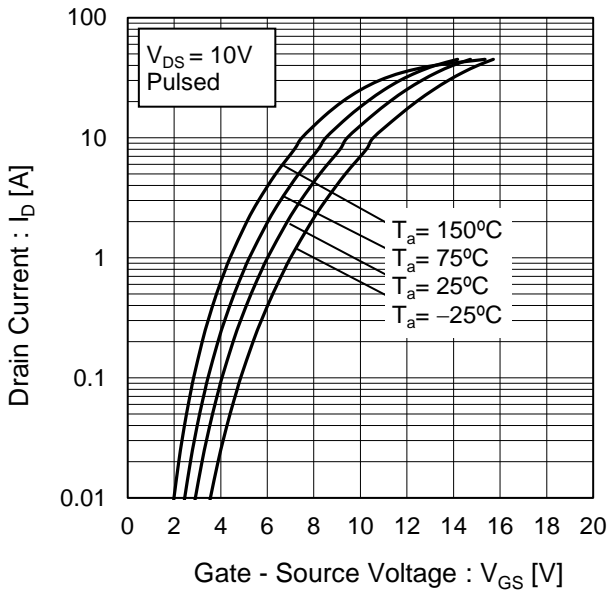


Fig.9 Typical Transfer Characteristics (II)

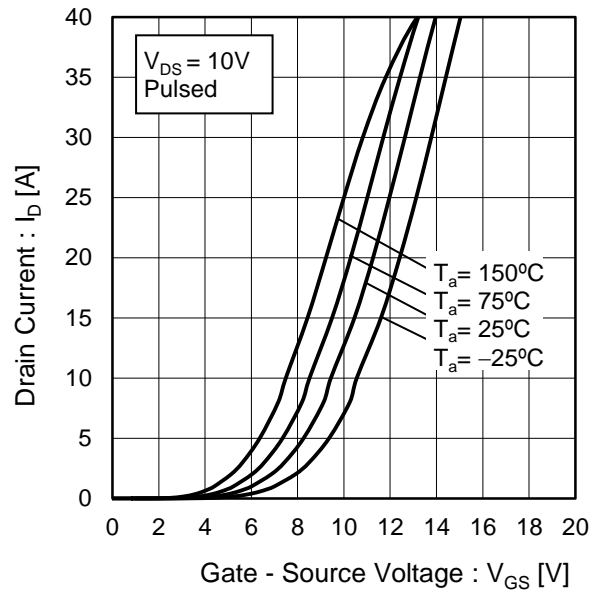


Fig.10 Gate Threshold Voltage vs. Junction Temperature

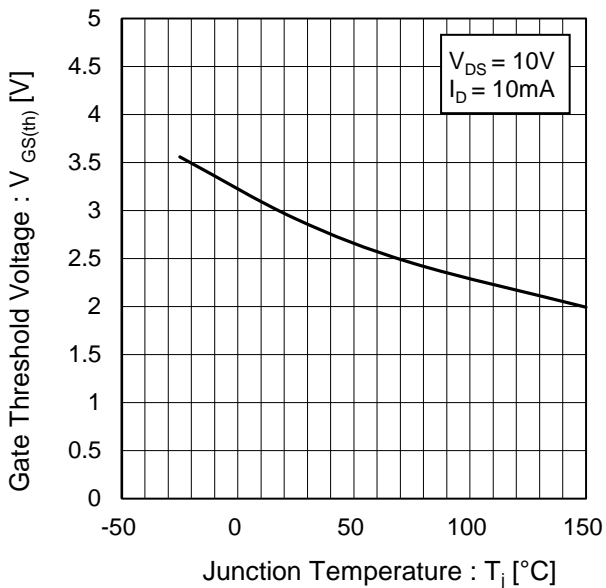
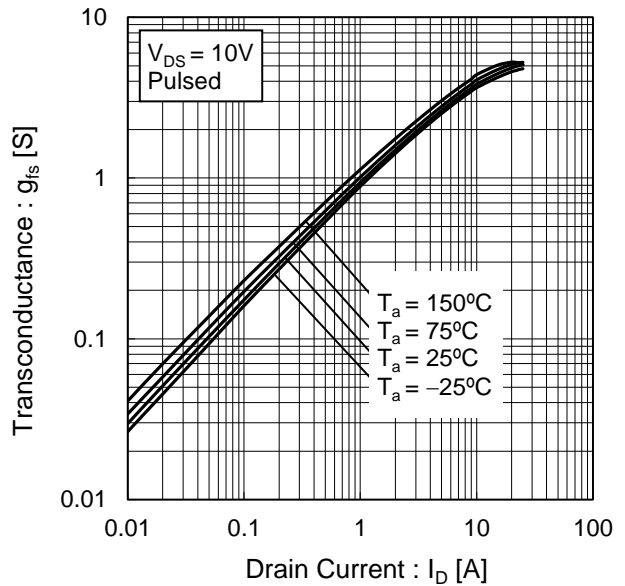


Fig.11 Transconductance vs. Drain Current



●Electrical characteristic curves

Fig.12 Static Drain - Source On - State Resistance vs. Gate - Source Voltage

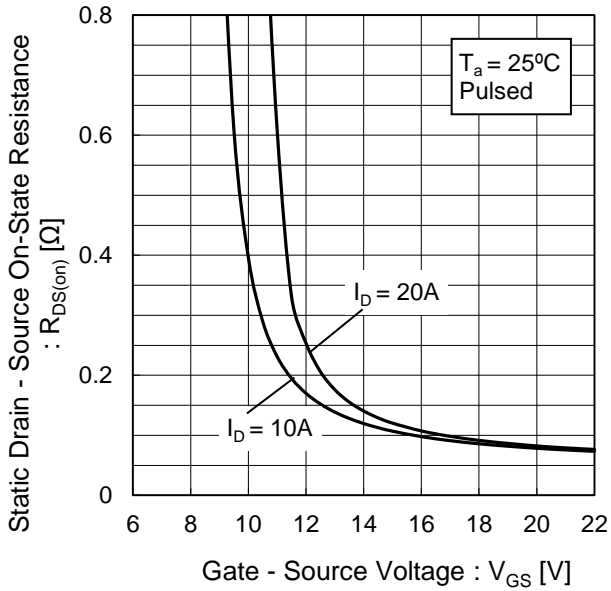


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

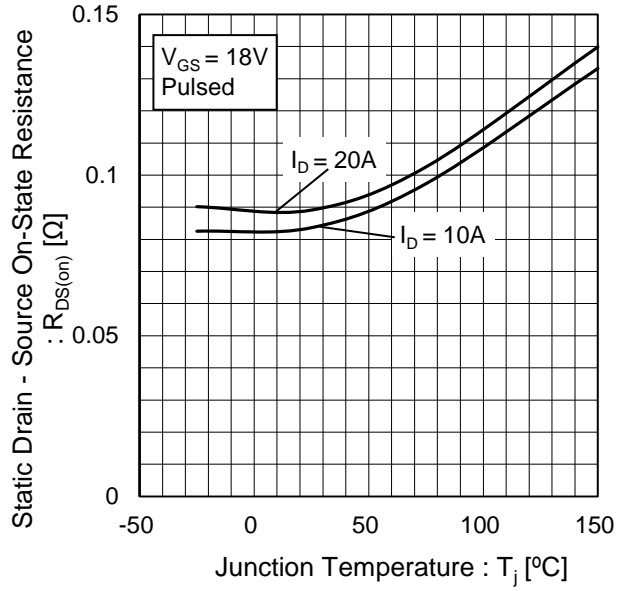
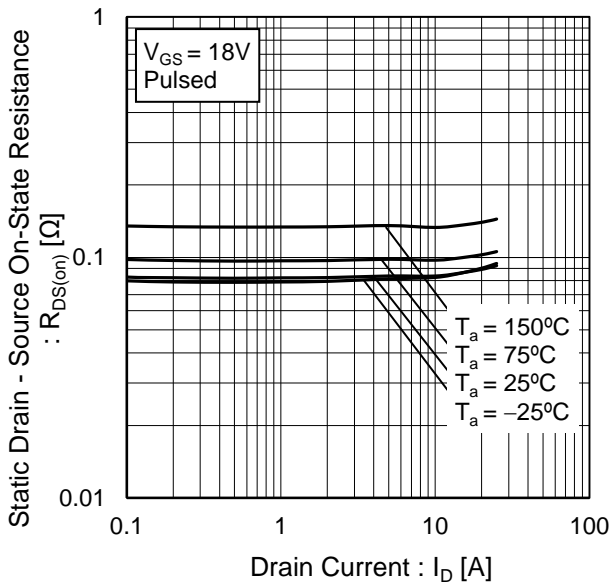


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current





●Electrical characteristic curves

Fig.15 Typical Capacitance vs. Drain - Source Voltage

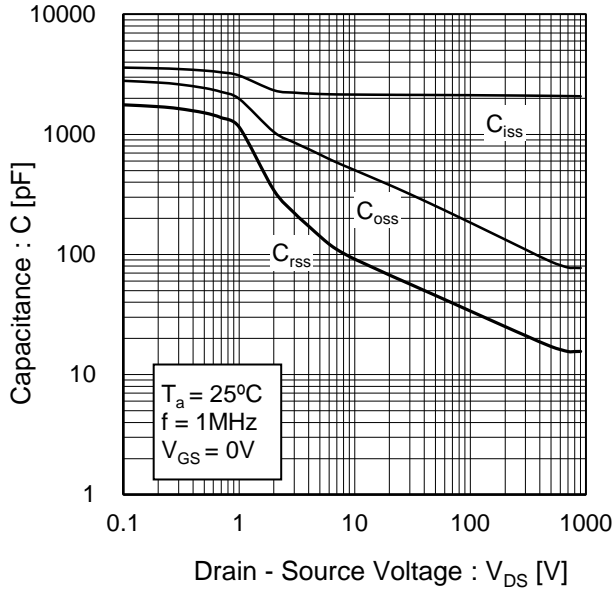


Fig.16 Coss Stored Energy

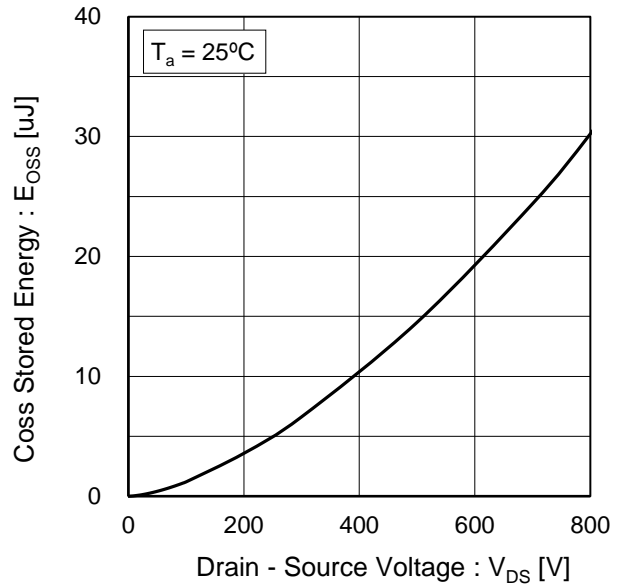


Fig.17 Switching Characteristics

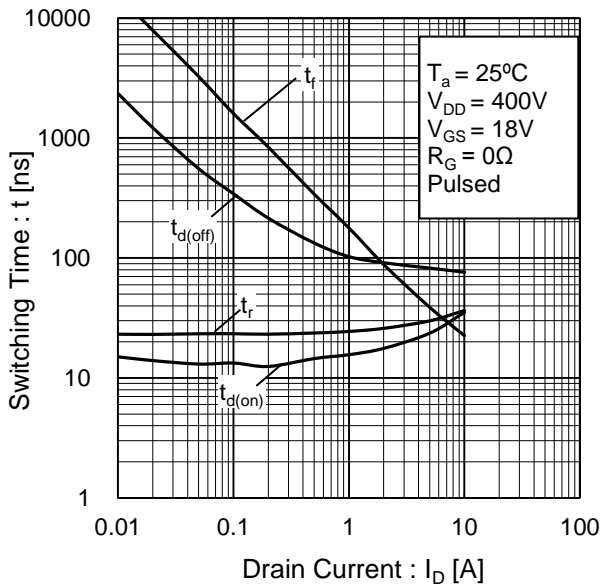
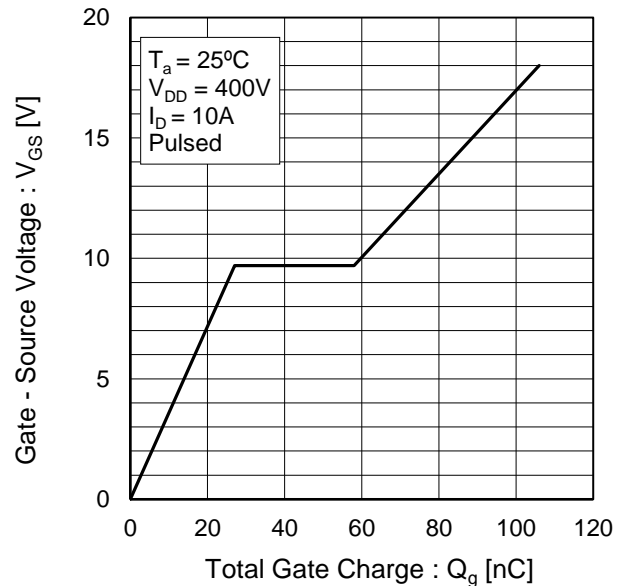


Fig.18 Dynamic Input Characteristics



●Electrical characteristic curves

Fig.19 Typical Switching Loss vs. Drain - Source Voltage

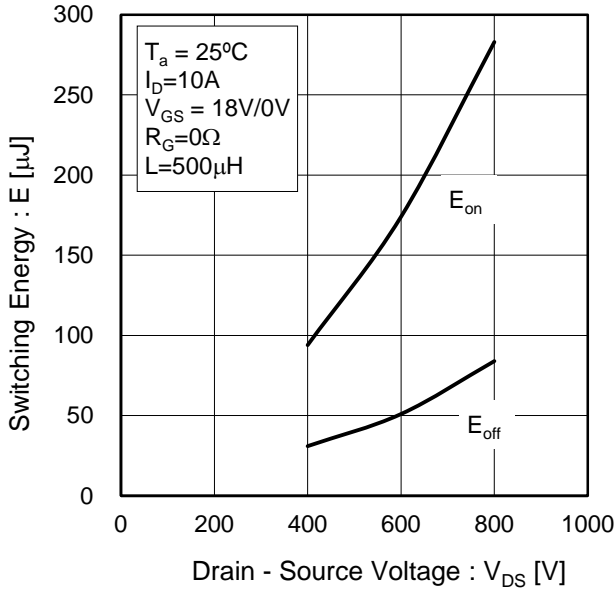


Fig.20 Typical Switching Loss vs. Drain Current

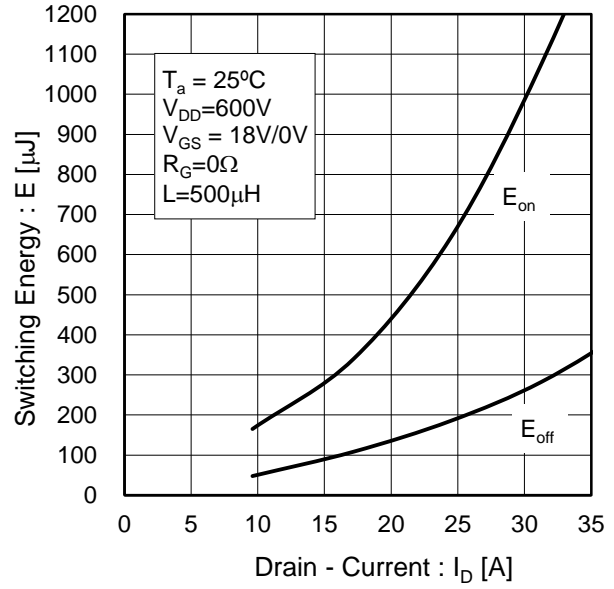
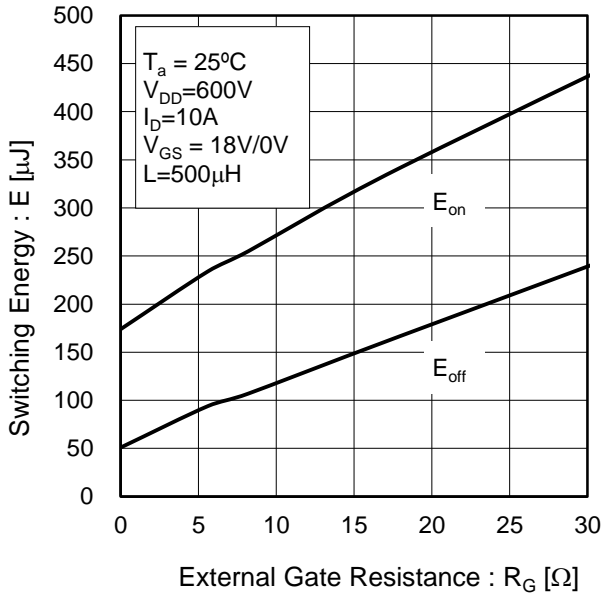


Fig.21 Typical Switching Loss vs. External Gate Resistance



●Electrical characteristic curves

Fig.22 Inverse Diode Forward Current vs. Source - Drain Voltage

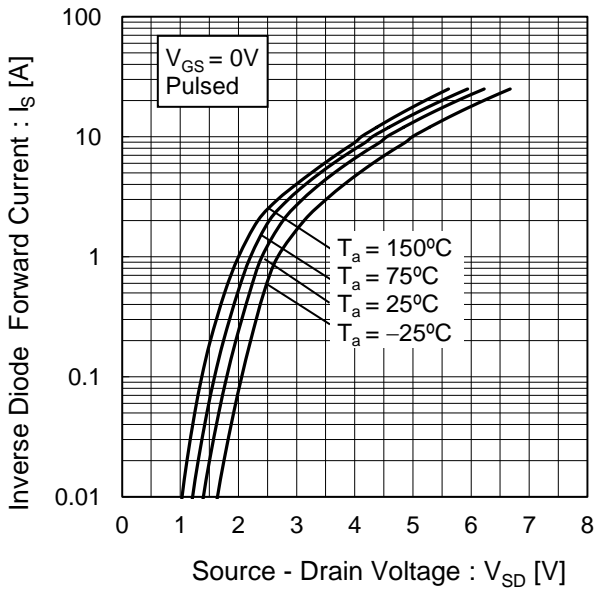
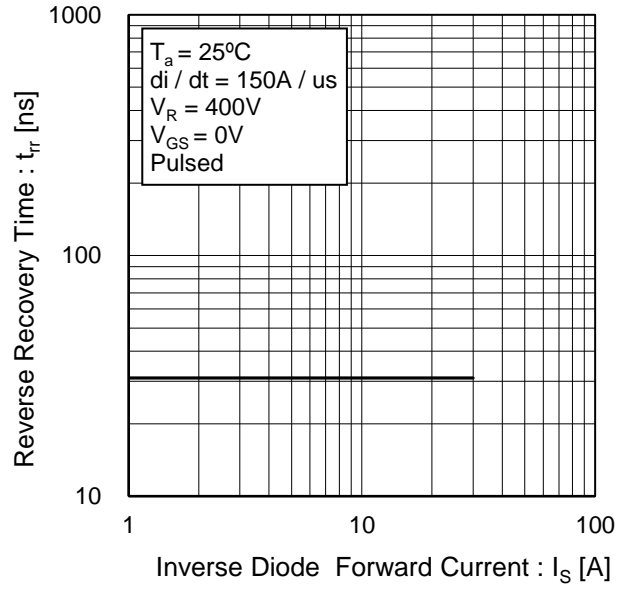


Fig.23 Reverse Recovery Time vs. Inverse Diode Forward Current



● Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

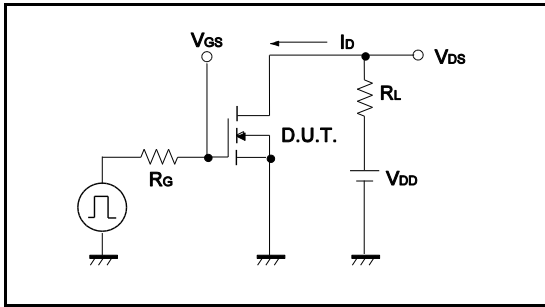


Fig.1-2 Switching Waveforms

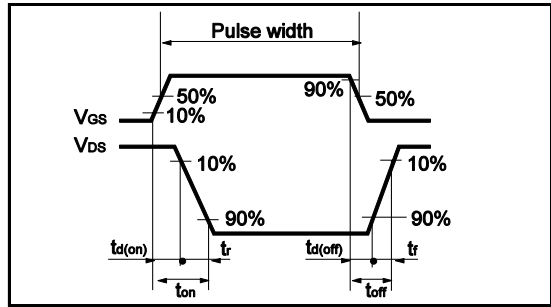


Fig.2-1 Gate Charge Measurement Circuit

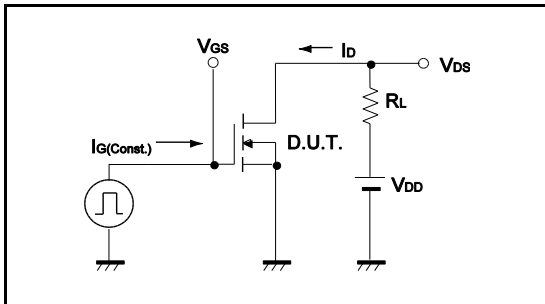


Fig.2-2 Gate Charge Waveform

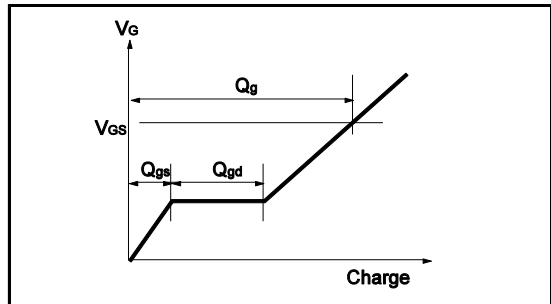


Fig.3-1 Switching Energy Measurement Circuit

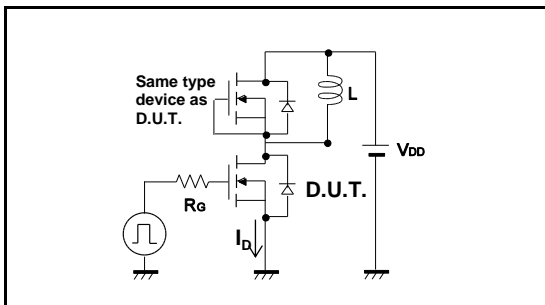


Fig.3-2 Switching Waveforms

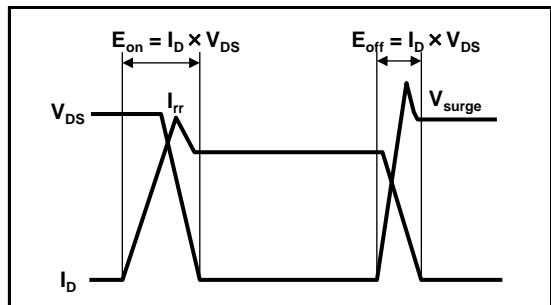


Fig.4-1 Reverse Recovery Time Measurement Circuit

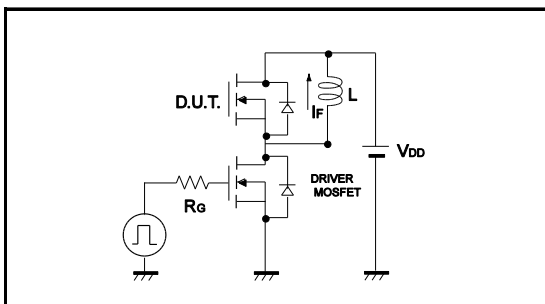
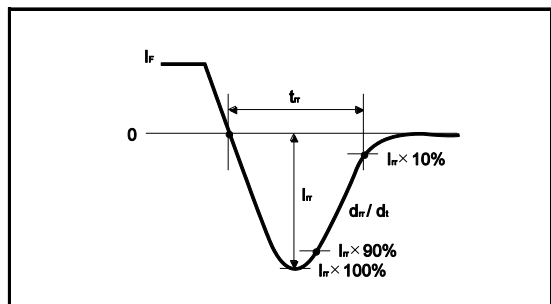
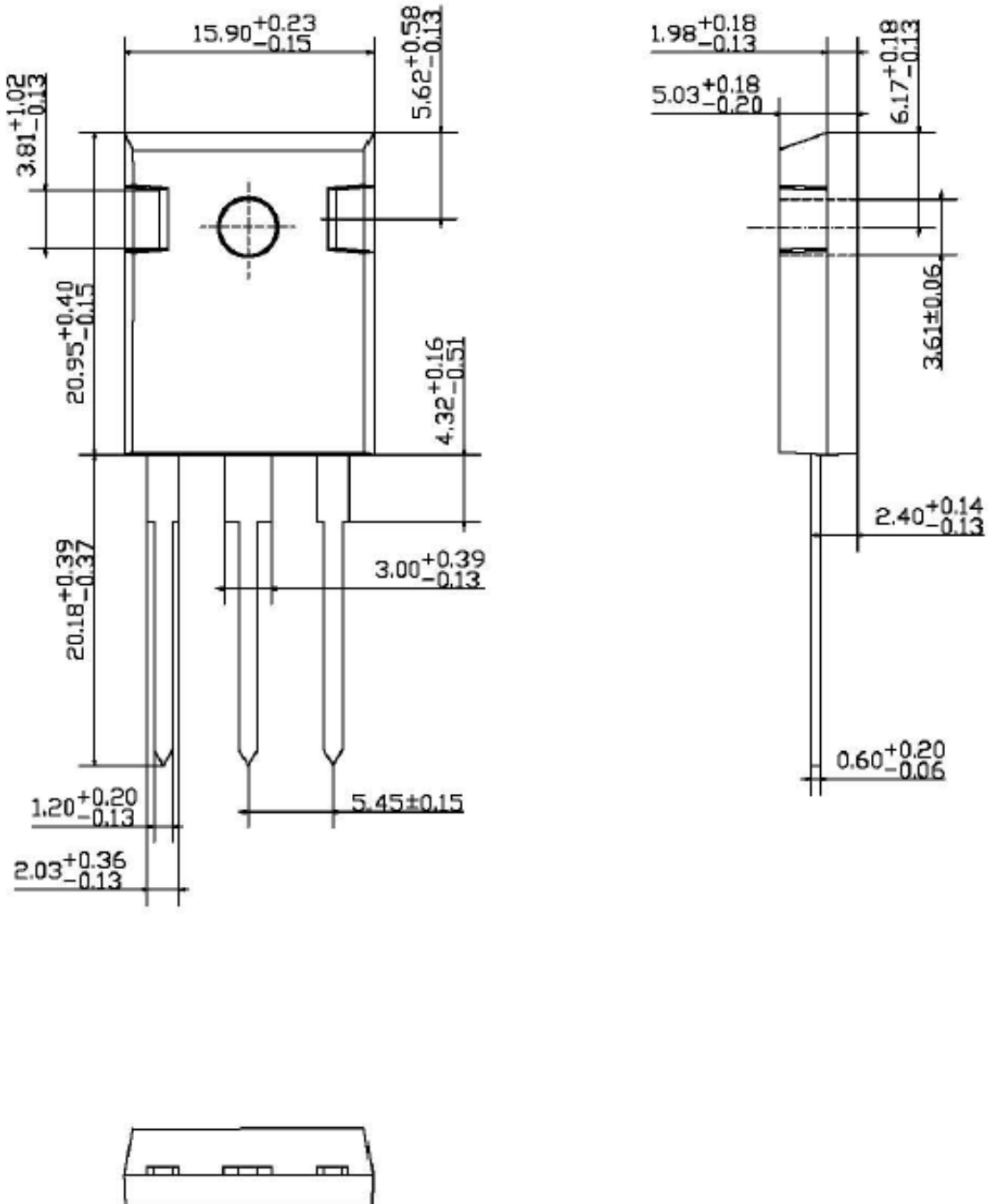


Fig.4-2 Reverse Recovery Waveform



●Dimensions (Unit : mm)

TO-247



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